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(54) **SEMICONDUCTOR DEVICE**

(57) Abstract:

**PURPOSE:** To reduce the size of a package by forming a chip wherein the circuit function of a semiconductor device is divided into two chips, and sealing said chips which are stacked in the same package.

**CONSTITUTION:** The title semiconductor device is formed by dividing a chip constituting a circuit into two chips, and sealing the divided chips which are stacked. Thereby a chip size is restrained and the defective rate can be decreased. Since the package size is reduced, the mounting area can be made small.

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